

PMP10487 REV D Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	Package
C1, C6, C8, C9	4	0.1uF	C1608X7R1H104K	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
C2, C3	2	10uF	GMK316AB7106KL	Taiyo Yuden	CAP, CERM, 10 µF, 35 V, +/- 10%, X7R, 1206	1206
C4	1		DNP		CAP, AL, open, SMD	SMT Radial D
C5, C10	2	1uF	GRM21BR71C105KA01L	MuRata	CAP, CERM, 1 μF, 16 V, +/- 10%, X7R, 0805	0805
C7	1		DNP		CAP, open, 0603	0603
C100	1	1500pF	C1608C0G1H152J	TDK	CAP, CERM, 1500 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
D1	1	40V	B140-13-F	Diodes Inc.	Diode, Schottky, 40 V, 1 A, SMA	SMA
D2	1	24V	SMAJ24A-13-F	Diodes Inc.	Diode, TVS, Uni, 24 V, 400 W, SMA	SMA
D3	1	White	XPGBWT-01-0000-00HE3	Cree	LED, White, 5000K, SMD	3.45x3.45mm
D4	1		DNP		Diode, Schottky, SMA	SMA
J2	1		DNP		Terminal Block, 3.5mm Pitch, 2x1, TH	7.0x8.2x6.5mm
L1	1	22uH	MSS7341-223MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 22 µH, 1.41 A, 0.08 ohm, SMD	MSS7341
R1	1	0.15	WSL1206R1500FEA	Vishay-Dale	RES, 0.15, 1%, 0.25 W, 1206	1206
R2	1	38.3k	CRCW060338K3FKEA	Vishay-Dale	RES, 38.3 k, 1%, 0.1 W, 0603	0603
R3	1	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9 k, 1%, 0.1 W, 0603	0603
R4	1		DNP		RES, open, 0603	0603
R5	1		DNP		RES, open, 0603	0603
R6	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R100	1	57.6k	CRCW060357K6FKEA	Vishay-Dale	RES, 57.6 k, 1%, 0.1 W, 0603	0603
TP1, TP2, TP4	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
						Testpoint
TP6, TP10	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
						Testpoint
TP3, TP5, TP7,	4		DNP		Test Point, Miniature, Red, TH	Red Miniature
TP8						Testpoint
TP9, TP11	2		DNP		Test Point, Miniature, Black, TH	Black Miniature
						Testpoint
U1	1		LM20323MH	Texas Instruments	36V,3A PowerWise 500 kHz Synchronous Buck Regulator Adjustable	MXA20A
					Frequency Synchronous Buck Regulator, 20-pin TSSOP-EP	
U2	1		INA193AIDBVR	Texas Instruments	CURRENT SHUNT MONITOR -16V to +80V Common-Mode Range,	DBV0005A
					DBV0005A	

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